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10/052,703	01/16/2002	Sang-Bom Kang	9898-207	1366
7590 03/02/2004 MARGER JOHNSON & McCOLLOM, P.C.			EXAMINER	
			ZERVIGON, RUDY	
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Please find below and/or attached an Office communication concerning this application or proceeding.

	#W				
	Application No.	Applicant(s)			
	10/052,703	KANG ET AL.			
Office Action Summary	Examiner	Art Unit			
-	Rudy Zervigon	1763			
The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply					
A SHORTENED STATUTORY PERIOD FOR REPLY THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.1 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply If NO period for reply is specified above, the maximum statutory period of Failure to reply within the set or extended period for reply will, by statute Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	36(a). In no event, however, may a reply be y within the statutory minimum of thirty (30) d will apply and will expire SIX (6) MONTHS from a cause the application to become ABANDON	timely filed ays will be considered timely. om the mailing date of this communication. NED (35 U.S.C. § 133).			
Status					
1) Responsive to communication(s) filed on 12 D					
	action is non-final.				
3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is					
closed in accordance with the practice under E	<u>-x paπe Quayle, 1935 C.D. 11, </u>	453 O.G. 213.			
Disposition of Claims					
 4) ☐ Claim(s) 1-40 is/are pending in the application 4a) Of the above claim(s) 38-40 is/are withdraw 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 1-37 is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction and/or 	vn from consideration.				
Application Papers					
9) The specification is objected to by the Examine					
10)☐ The drawing(s) filed on is/are: a)☐ accepted or b)☐ objected to by the Examiner.					
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).					
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d). 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.					
Priority under 35 U.S.C. § 119					
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority document 2. Certified copies of the priority document 3. Copies of the certified copies of the priority document application from the International Bureat* * See the attached detailed Office action for a list	ts have been received. ts have been received in Application of the contract of	ation No ived in this National Stage			
Attachment(s)					
1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08 Paper No(s)/Mail Date	4) Interview Summa Paper No(s)/Mail 5) Notice of Informa 6) Other:				

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DETAILED ACTION

Election/Restrictions

1. Applicant's election without traverse of Claims 1-37 is acknowledged.

Claim Rejections - 35 USC § 102

- 2. The text of those sections of Title 35, U.S. Code not included in this action can be found in a prior Office action.
- Claims 1-9, 12, 14, 15, and 19 are rejected under 35 U.S.C. 102(b) as being anticipated by Chen et al (USPat. 4,534,816). Chen teaches a shower head (14, 16, 12; Figure 1; column 3, lines 20-48) for supplying a reaction gas ("Reactive Gas", 18; Figure 1; column 3, lines 20-48) to a wafer in a process chamber (30; Figure 1; column 4, lines 1-29), the shower head (14, 16, 12; Figure 1; column 3, lines 20-48) comprising: a plurality of plates (14, 16, 12; Figure 1; column 3, lines 20-48) comprising gas paths (54; Figure 1-4; column 4, lines 56-69) for supplying a reaction gas ("Reactive Gas", 18; Figure 1; column 3, lines 20-48) to a wafer; and a cooling system (22, 56; Figure 1, 3-6; column 5, lines 3-28) comprising a plurality of coolant inlets (56; Figure 5; column 5, lines 3-28) and a plurality of coolant outlets (62; Figure 5; column 5, lines 3-28) formed in a lower one (12; Figure 6; column 4, lines 56-68) of the plurality of plates (14, 16, 12; Figure 1; column 3, lines 20-48), and further comprising a plurality of inner cooling lines (channel between 56 and 62; Figure 5) configured to connect each of the plurality of coolant inlets (56; Figure 5; column 5, lines 3-28) to one of the plurality of coolant outlets (62; Figure 5; column 5, lines 3-28), as claimed by claim 1.

Chen teaches:

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- i. A shower head (14, 16, 12; Figure 1; column 3, lines 20-48) according to claim 1, wherein the plurality of coolant inlets (56; Figure 5; column 5, lines 3-28) and the plurality of coolant outlets (62; Figure 5; column 5, lines 3-28) are formed on a side of the lower plate (12; Figure 6; column 4, lines 56-68), as claimed by claim 2
- ii. A shower head (14, 16, 12; Figure 1; column 3, lines 20-48) according to claim 1, wherein at least four coolant inlets (56; Figure 5; column 5, lines 3-28), at least four coolant outlets (62; Figure 5; column 5, lines 3-28), and at least four inner cooling lines (channel between 56 and 62; Figure 5) are formed, as claimed by claim 3
- iii. A shower head (14, 16, 12; Figure 1; column 3, lines 20-48) according to claim 1, wherein the plurality of coolant inlets (56; Figure 5; column 5, lines 3-28) are formed on a first side of the lower plate (12; Figure 6; column 4, lines 56-68), the plurality of coolant outlets (62; Figure 5; column 5, lines 3-28) are formed on a second side of the lower plate (12; Figure 6; column 4, lines 56-68), and the plurality of inner cooling lines (channel between 56 and 62; Figure 5) are formed parallel to each other, as claimed by claim 4
- first coolant inlet (any of 62; Figure 5; column 5, lines 3-28) is connected to a first coolant outlet (any of 56; Figure 5; column 5, lines 3-28) by a first inner cooling line (channel between any of 56 and any of 62; Figure 5), wherein a second coolant outlet (any other of 62; Figure 5; column 5, lines 3-28) is connected to a second coolant inlet (any other of 56; Figure 5; column 5, lines 3-28) by a second inner cooling line (any other channel between any of 56 and any of 62; Figure 5), and wherein the second coolant outlet (any other of 62; Figure 5; column 5, lines 3-28) is located adjacent to the first coolant inlet (any of

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62; Figure 5; column 5, lines 3-28) on a first side of the lower plate (12; Figure 6; column 4, lines 56-68), as claimed by claim 5

- v. A shower head (14, 16, 12; Figure 1; column 3, lines 20-48) according to claim 1, wherein a first coolant outlet (any of 56; Figure 5; column 5, lines 3-28) is connected to a first coolant inlet (any of 62; Figure 5; column 5, lines 3-28) by a first inner cooling line (channel between any of 56 and any of 62; Figure 5), and wherein the first coolant outlet (any of 56; Figure 5; column 5, lines 3-28) is positioned approximately 90 degrees from a position of the first coolant inlet (any of 62; Figure 5; column 5, lines 3-28) along an circumferential edge of the lower plate (12; Figure 6; column 4, lines 56-68), as claimed by claim 6
- vi. A shower head (14, 16, 12; Figure 1; column 3, lines 20-48) according to claim 6, wherein a second coolant inlet (any other of 56; Figure 5; column 5, lines 3-28) is located adjacent to the first coolant outlet (any of 56; Figure 5; column 5, lines 3-28), wherein the second coolant outlet (any other of 62; Figure 5; column 5, lines 3-28) is connected to a second coolant inlet (any other of 56; Figure 5; column 5, lines 3-28) by a second inner cooling line (any other channel between any of 56 and any of 62; Figure 5), and wherein the second coolant outlet (any other of 62; Figure 5; column 5, lines 3-28) is located approximately 90 degrees from a position of the second coolant inlet (any other of 56; Figure 5; column 5, lines 3-28) along the edge of the lower plate (12; Figure 6; column 4, lines 56-68), and wherein the second coolant outlet (any other of 62; Figure 5; column 5, lines 3-28) is located approximately 180 degrees from the first coolant inlet (any of 62; Figure 5; column 5, lines 3-28) along the edge of the lower plate (12; Figure 6; column 4, lines 56-68), as claimed by claim 7 compare Figure 5 of Chen with Figure 4 of the present application

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vii. A shower head (14, 16, 12; Figure 1; column 3, lines 20-48) according to claim 1, further comprising: a first outer cooling line (66; Figure 5) arranged outside the lower plate (12; Figure 6; column 4, lines 56-68) to connect the plurality of coolant inlets (56; Figure 5; column 5, lines 3-28); and a second outer cooling line (68; Figure 5) arranged outside the lower plate (12; Figure 6; column 4, lines 56-68) to connect the plurality of coolant outlets (62; Figure 5; column 5, lines 3-28), as claimed by claim 8

an apparatus comprising: a process chamber (30; Figure 1; column 4, lines 1-29); a heater viii. stage (40; Figure 1; column 4, lines 29-39) located in a lower portion of the process chamber (30; Figure 1; column 4, lines 1-29), said heater stage (40; Figure 1; column 4, lines 29-39) configured to support a wafer and to heat the wafer to a high temperature; a shower head (14, 16, 12; Figure 1; column 3, lines 20-48) located in an upper portion of the process chamber (30; Figure 1; column 4, lines 1-29), said shower head (14, 16, 12; Figure 1; column 3, lines 20-48) configured to supply a reaction gas ("Reactive Gas", 18; Figure 1; column 3, lines 20-48) to the wafer; and a rimshaped separating device (44; Figure 1; column 3, lines 62-69) arranged between the process chamber (30; Figure 1; column 4, lines 1-29) and the heater stage (40; Figure 1; column 4, lines 29-39) - compare Figure 1 of Chen with Figure 1 of the present Application, said rimshaped separating device (44; Figure 1; column 3, lines 62-69) configured to separate the heater stage (40; Figure 1; column 4, lines 29-39) from the process chamber (30; Figure 1; column 4, lines 1-29) and to reduce a volume of processing space within the process chamber (30; Figure 1; column 4, lines 1-29), as claimed by claim 9 -That Applicant claims an apparatus for forming a thin film is a statement of intended use of the apparatus. It is well established that apparatus claims must be structurally distinguished

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from the prior art (In re Danley, 120 USPQ 528, 531 (CCPA 1959). "Apparatus claims cover what a device is, not what a device does ."(emphasis in original) Hewlett - Packard Co . v. Bausch & Lomb Inc ., 15 USPQ2d 1525, 1528 (Fed. Cir. 1990), MPEP – 2114). Further, a claim containing a "recitation with respect to the manner in which a claimed apparatus is intended to be employed does not differentiate the claimed apparatus from a prior art apparatus" if the prior art apparatus teaches all the structural limitations of the claim. Exparte Masham, 2 USPQ2d 1647 (Bd. Pat. App. & Inter. 1987).

- ix. An apparatus according to claim 9, wherein the rimshaped separating device (44; Figure 1; column 3, lines 62-69) is configured to separate the heater stage (40; Figure 1; column 4, lines 29-39) and the process chamber (30; Figure 1; column 4, lines 1-29) by a uniform distance, as claimed by claim 12
- x. An apparatus according to claim 9, wherein the rimshaped separating device (44; Figure 1; column 3, lines 62-69) is formed of a heat-resistant material (column 6, lines 5-15), as claimed by claim 14
- xi. An apparatus according to claim 14, wherein the heat-resistant material (column 6, lines 5-15) is a ceramic material ("glass ceramic, quartz..."; column 6, lines 5-15), as claimed by claim 15
- An apparatus according to claim 9, further comprising a process chamber (30; Figure 1; column 4, lines 1-29) cooling system (52; Figure 1, column 4, lines 29-39) configured to cool a bottom surface of the process chamber (30; Figure 1; column 4, lines 1-29) whereon the rimshaped separating device (44; Figure 1; column 3, lines 62-69) is located, as claimed by claim 19

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Claim Rejections - 35 USC § 103

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 2. Claims 10, 11, 13, 16-18, and 20-37 are rejected under 35 U.S.C. 103(a) as being unpatentable over Chen et al (USPat. 4,534,816) in view of Sato (USPat. 6,120,605). Chen is discussed above. Chen further teaches an apparatus further comprising the process chamber (30; Figure 1; column 4, lines 1-29) cooling system (22, 56; Figure 1, 3-6; column 5, lines 3-28) arranged in thermal communication with the lower portion of the process chamber (30; Figure 1; column 4, lines 1-29), said lower portion of the process chamber (30; Figure 1; column 4, lines 1-29) supporting the rimshaped separating device (44; Figure 1; column 3, lines 62-69). Chen does not teach his operating temperature.

Chen further does not teach:

- i. Chen's rimshaped separating device (44; Figure 1; column 3, lines 62-69) contacts Chen's bottom of Chen's heater stage (40; Figure 1; column 4, lines 29-39), as claimed by claim 11, 34
- ii. An apparatus according to claim 12, wherein Chen's heater stage (40; Figure 1; column 4, lines 29-39) and Chen's process chamber (30; Figure 1; column 4, lines 1-29) are separated by about 2-10 cm, as claimed by claim 13, 31

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- iii. Chen's rimshaped separating device (44; Figure 1; column 3, lines 62-69) is configured to closely adhere to Chen's bottom of Chen's heater stage (40; Figure 1; column 4, lines 29-39), as claimed by claim 16
- iv. a shaft installed beneath Chen's heater stage (40; Figure 1; column 4, lines 29-39) and configured to raise and lower Chen's heater stage (40; Figure 1; column 4, lines 29-39); and the shaft introduction portion configured to introduce a shaft at a bottom of Chen's process chamber (30; Figure 1; column 4, lines 1-29), as claimed by claim 17
- v. An apparatus according to claim 17, wherein the shaft introduction portion is formed as a flexible bellows and has a length that varies as the shaft is raised and lowered, as claimed by claim 18, and 36
- vi. Chen's heater stage (40; Figure 1; column 4, lines 29-39) to separate Chen's space beneath Chen's heater stage (40; Figure 1; column 4, lines 29-39) from Chen's process chamber (30; Figure 1; column 4, lines 1-29) space containing Chen's wafer to reduce Chen's process volume of Chen's process chamber (30; Figure 1; column 4, lines 1-29), as claimed by claim 20 That Applicant claims an apparatus for forming Chen's thin film is Chen's statement of intended use of Chen's apparatus. It is well established that apparatus claims must be structurally distinguished from the prior art (In re Danley, 120 USPQ 528, 531 (CCPA 1959). "Apparatus claims cover what a device is, not what a device does ."(emphasis in original) Hewlett Packard Co . v. Bausch & Lomb Inc ., 15 USPQ2d 1525, 1528 (Fed. Cir. 1990), MPEP 2114). Further, a claim containing a "recitation with respect to the manner in which a claimed apparatus is intended to be employed does not differentiate the claimed apparatus

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from a prior art apparatus" if the prior art apparatus teaches all the structural limitations of the claim. Exparte Masham, 2 USPQ2d 1647 (Bd. Pat. App. & Inter. 1987).

Sato teaches an operating temperature of 360°C (column 7, lines 48-51) including:

- vii. Sato's rimshaped separating device (lowest portion of 11; Figure 1) contacts Sato's bottom of Sato's heater stage (17; Figure 1; column 4, lines 44-65), as claimed by claim 11, 34
- viii. An apparatus according to claim 12, wherein Sato's heater stage (17; Figure 1; column 4, lines 44-65) and Sato's process chamber (10; Figure 1; column 4, lines 44-65) are separated by about 2-10 cm, as claimed by claim 13, 31
 - Sato's rimshaped separating device (lowest portion of 11; Figure 1) is configured to closely adhere to Sato's bottom of Sato's heater stage (17; Figure 1; column 4, lines 44-65), as claimed by claim 16
 - x. a shaft (15; Figure 1; column 4, lines 44-65) installed beneath Sato's heater stage (17; Figure 1; column 4, lines 44-65) and configured to raise and lower Sato's heater stage (17; Figure 1; column 4, lines 44-65); and the shaft (15; Figure 1; column 4, lines 44-65) introduction portion configured to introduce a shaft (15; Figure 1; column 4, lines 44-65) at a bottom of Sato's process chamber (10; Figure 1; column 4, lines 44-65), as claimed by claim 17
 - xi. An apparatus according to claim 17, wherein the shaft (15; Figure 1; column 4, lines 44-65) introduction portion is formed as a flexible bellows (22; Figure 1; column 4, lines 44-65) and has a length that varies as the shaft (15; Figure 1; column 4, lines 44-65) is raised and lowered, as claimed by claim 18, and 36
- xii. Sato's heater stage (17; Figure 1; column 4, lines 44-65) to separate Sato's space beneath Sato's heater stage (17; Figure 1; column 4, lines 44-65) from Sato's process chamber (10;

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Figure 1; column 4, lines 44-65) space containing Sato's wafer to reduce Sato's process volume of Sato's process chamber (10; Figure 1; column 4, lines 44-65), as claimed by claim 20 – That Applicant claims an apparatus for forming Sato's thin film is Sato's statement of intended use of Sato's apparatus. It is well established that apparatus claims must be structurally distinguished from the prior art (In re Danley, 120 USPQ 528, 531 (CCPA 1959). "Apparatus claims cover what a device is, not what a device does ."(emphasis in original) Hewlett - Packard Co . v. Bausch & Lomb Inc ., 15 USPQ2d 1525, 1528 (Fed. Cir. 1990), MPEP – 2114). Further, a claim containing a "recitation with respect to the manner in which a claimed apparatus is intended to be employed does not differentiate the claimed apparatus from a prior art apparatus" if the prior art apparatus teaches all the structural limitations of the claim. Exparte Masham, 2 USPQ2d 1647 (Bd. Pat. App. & Inter. 1987).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to replace Chen's wafer supporting and heating structure with Sato's supporting and heating structure as discussed above to process a wafer at optimal temperatures.

Motivation to replace Chen's wafer supporting and heating structure with Sato's wafer supporting and heating structure as discussed above to process a wafer at optimal temperatures as discussed above is to provide and alternate and equivalent means for wafer supporting and heating. Further, it would be obvious to those of ordinary skill in the art to optimize the operation of the claimed invention (In re Boesch, 617 F.2d 272, 205 USPQ 215 (CCPA 1980); In re Hoeschele , 406 F.2d 1403, 160 USPQ 809 (CCPA 1969); Merck & Co. Inc . v. Biocraft Laboratories Inc. , 874 F.2d 804, 10 USPQ2d 1843 (Fed. Cir.), cert. denied , 493 U.S. 975 (1989); In re Kulling , 897 F.2d 1147, 14 USPQ2d 1056 (Fed. Cir. 1990), MPEP 2144.05).

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Response to Arguments

- 3. Applicant's arguments filed December 12, 2003 have been fully considered but they are not persuasive.
- 4. Applicant states:

For the above reasons, Chen does not teach the claim 1 features of a plurality of coolant inlets, a plurality of coolant outlets, or a plurality of inner cooling lines.

Applicant bases the above position on Applicant's analysis of Chen on page 9 (last three paragraphs). However, the Examiner believes Applicant is not addressing the specific claim limitations Applicant is arguing: As discussed above and in the prior action on the merits, Chen specifically teaches:

a cooling system (22, 56; Figure 1, 3-6; column 5, lines 3-28) comprising a plurality of coolant inlets (56; Figure 5; column 5, lines 3-28)

Compare the Examiner's citation of Chen's coolant inlets (56; Figure 5) with Applicant's specific definition in the specification:

Referring to FIG. 2, a primary cooling inlet 410a may supply coolant to a plurality of coolant inlets 411.

"[0033]

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The Examiner:

"

and a plurality of coolant outlets (62; Figure 5; column 5, lines 3-28) formed in a lower one (12;

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Figure 6; column 4, lines 56-68) of the plurality of plates (14, 16, 12; Figure 1; column 3, lines

20-48)

Compare the Examiner's citation of Chen's coolant outlets (62; Figure 5) with Applicant's

specific definition in the specification:

"

The coolant travels through the inner cooling lines 450 in the third plate 350 to a plurality of

coolant outlets 415.

"[0033]

The Examiner:

"

and further comprising a plurality of inner cooling lines (channel between 56 and 62; Figure 5)

configured to connect each of the plurality of coolant inlets (56; Figure 5; column 5, lines 3-28)

to one of the plurality of coolant outlets (62; Figure 5; column 5, lines 3-28)

"

Applicant disagrees with the Examiner's citation of Chen's heater 40. However, Chen 5.

specifically teaches that Chen's portion 40; Figure 1; column 4, lines 29-39 as being a

component of an electrode structure. Thus Chen's teaching directly coincides with Applicant's

heater definition:

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"

Electrodes (not shown) are built into the heater stage 600 to apply a bias to the wafer 100.

"[0026]

6. Applicant's states:

"

Contrary to the recited features of claim 9 that are illustrated in applicants' FIG. 1, Chen's insulating ring 44 is not arranged between a bottom of the outer housing 30 and a bottom of lower electrode assembly 38. Indeed, Chen's insulating ring 44 is arranged on an upper surface of the upper section 40. The Examiner has also agreed that the surface between..

"

The Examiner disagrees. Chen clearly shows a separating device (44; Figure 1; column 3, lines 62-69) arranged (positioned) between a bottom (lowest surface) of the process chamber (30; Figure 1; column 4, lines 1-29) and a bottom (lowest surface) of the heater stage (40; Figure 1; column 4, lines 29-39).

Conclusion

7. THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period

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will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

8. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Examiner Rudy Zervigon whose telephone number is (571) 272.1442. The examiner can normally be reached on a Monday through Thursday schedule from 8am through 7pm. The official after fax phone number for the 1763 art unit is (703) 872-9306. Any Inquiry of a general nature or relating to the status of this application or proceeding should be directed to the Chemical and Materials Engineering art unit receptionist at (571) 272-1700. If the examiner can not be reached please contact the examiner's supervisor, Gregory L. Mills, at (571) 272-1439.

JEFFRIE R. LUND PRIMARY EXAMINER